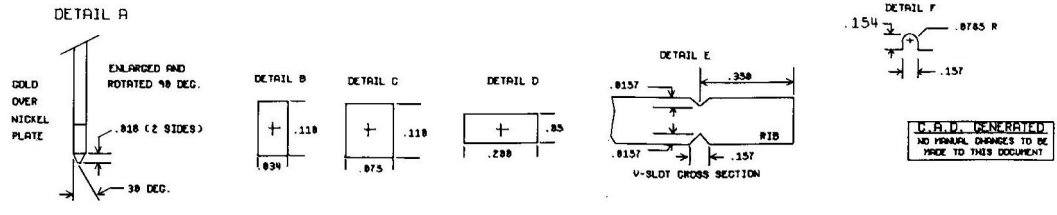


NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARDS SHALL BE FABRICATED WITH THE BEST COMMERCIAL PRACTICES. FABRICATE PER COMMODORE SPEC. NO. 1.01.007.
- MATERIAL:
 - BASE LAMINATE: COPPER CLAD, GLASS BASE, EPOXY RESIN. (FIBER OR GEL) 100% COPPER ON EXTERNAL LAYERS. PER MIL-P-13494.
 - THICKNESS AND ACCUMULATION OF INDIVIDUAL LAYER TOLERANCES SHALL BE OPTIMIZED TO ACHIEVE AN OVERALL THICKNESS OF 1.57 (±0.062).
- PLATING EXTERNAL LAYERS AND THRU HOLES:
 - THE HOLE WALLS SHALL BE PREPARED FOR PLATING BY SENSITIZING WITH ELECTROLESS COPPER, PROVIDING THE CONDUCTIVE BASE FOR SUBSEQUENT PLATING.
 - ELECTRO-DEPOSITED COPPER SHALL BE IN ACCORDANCE WITH MIL-C-14550, CLASS 1, 0.025 (±0.001) MINIMUM THICKNESS.
 - SOLDER PLATE TO BE 60% TIN, 40% LEAD ± 10% AND SHALL BE AN AVERAGE MINIMUM THICKNESS OF 0.001 (±0.0002) WITH NO SINGLE PLACEMENT LESS THAN 0.0025 (±0.0001) AFTER REFLUX.
 - COPPER DEPOSITED ON SURFACE CONDUCTORS SHALL BE A MINIMUM THICKNESS OF 0.041 (±0.0024).
 - SOLDER PLATING SHALL COVER ALL EXPOSED COPPER ON TRACES AND PADS, WITH A MINIMUM AVERAGE THICKNESS OF 0.0025 (±0.0002) AFTER REFLUX.
 - THE PLATING SHALL BE HOMOGENEOUS AND COMPLETELY COVER CONDUCTORS WITHOUT PITTS, PINHOLES, OR OTHER NON-UNIFORMITIES.
 - RINGULAR RINGS SHALL BE COMPLETE AND UNBROKEN SURROUNDING EACH ROUND TERMINAL PAD BY A MINIMUM OF 0.050 (±0.002).
- CONNECTOR AREA:
 - LOW STRESS NICKEL PLATING SHALL BE A MINIMUM OF 0.0076 (±0.0003) AND 0.025 (±0.001) MAX IN ACCORDANCE DD-N-248 CLASS II, TYPE 1V.
 - GOLD PLATING SHALL BE A MINIMUM OF 0.0017 (±0.0003) AND SHALL BE IN ACCORDANCE WITH MIL-C-45248, TYPE II GRADE C, CLASS 1.
- HOLE LOCATIONS ARE NOT DIMENSIONED ARE TO BE CENTERED ON THE PAD AREA WITHIN 0.176 (±0.007) OF THE CENTER OF THE PAD.
- FRONT TO BACK REGISTRATION SHALL BE WITHIN 0.127 (±0.005).
- ALL DIMENSIONS ARE IN INCHES.
- ALL TOOLING HOLE DIAMETERS TO HAVE A TOLERANCE OF +0.000 (+0.0003), -0.000 (-0.000).
- ARTWORK PROVIDED PER COMMODORE SPEC. NO. 1.01.007 SECT. 4.2. THIS FAB. DMC. IS USED WITH ARTWORK NO. 312815.
- SILKSCREEN COMPONENT SIDE USING ARTWORK SUPPLIED. (WHITE)
- SOLDERMASK BOTH SIDES PER IP8-99040.
- HOLES INDICATED AS BEING ON GRID SHALL BE CENTERED WITHIN 0.076 (±0.003) OF THEIR TRUE POSITION POINT, REF. BY X-Y DATA.
- BOARDS SHALL BE IDENTIFIED WITH THE VENDORS U.L. REGISTERED LOGO ON THE COMPONENT SIDE.
- SOLDERMASK OVER BARE COPPER (BOTH SIDES).
- ALL BOARDS ARE TO BE ELECTRICALLY TESTED FOR CONTINUITY AND RESISTANCE PER MIL-P-55110 REV D OR TO 10 VOLTS, 2.5 MEG OHMS MINIMUM ISOLATION.

CODE/SYMBOL	HOLE SIZE IN. ±0.003	QUANTITY	PLATED/UNPLATED	REMARKS
□	.031	998		
□	.034	2		
□	.037	2108		
□	.042	238		
□	.052	19		
□	.089	9		
□	.125	12		
□	.125	15		TOOLING
□	.157	6		MOUNTING
B, C, D, F	DETAIL	11		SLOTS



NOTE: POSITION OF DETAIL B, C, D, F REFERENCED TO C/L

U. I. D. GENERATED
NO MANUAL CHANGES TO BE MADE TO THIS DOCUMENT

UNLESS OTHERWISE SPECIFIED, TOLERANCES ON DECIMALS	DESIGN BY: ZISKER	DATE: 6/23/51	
FR: ±0.125 IN: ±0.015 DEC: ±0.005	DATE: 6/23/51	APP: []	
MATERIAL: []	SCALE: 1:1	WELD ON: []	PCB FABRICATION AS00+ REV 8A PCB FAB SIZE: D 312814 REV: 1 SHEET 1 OF 1